

Dual N-Channel 60 V (D-S) 175 °C MOSFET

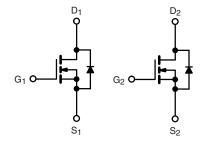
PRODUCT SUMMARY				
V _{DS} (V)	60			
$R_{DS(on)}(\Omega)$ at $V_{GS} = 10 \text{ V}$	0.028			
$R_{DS(on)}(\Omega)$ at $V_{GS} = 4.5 \text{ V}$	0.030			
I _D (A) per leg	7			
Configuration	Dual			

SO-8 Dual $\begin{array}{c} D_2 \\ D_2 \\ D_1 \\ 7 \\ 8 \\ \end{array}$ $\begin{array}{c} D_2 \\ 5 \\ \end{array}$ $\begin{array}{c} D_3 \\ G_2 \\ \end{array}$ $\begin{array}{c} 3 \\ G_2 \\ \end{array}$ $\begin{array}{c} G_2 \\ \end{array}$ $\begin{array}{c} Top \ View \\ \end{array}$

FEATURES

- TrenchFET® power MOSFET
- 100 % R_q and UIS tested





N-Channel MOSFET N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)					
PARAMETER	SYMBOL	LIMIT	UNIT		
Drain-Source Voltage		V _{DS}	60		
Gate-Source Voltage		V_{GS}	± 20	V	
Continuous Drain Current	T _C = 25 °C	1	7		
Continuous Drain Current	T _C = 125 °C	- I _D	4		
Continuous Source Current (Diode Conduction) a		I _S	3.6	Α	
Pulsed Drain Current ^b		I _{DM}	28		
Single Pulse Avalanche Current	L = 0.1 mH	I _{AS}	18		
Single Pulse Avalanche Energy	L = 0.1 IIII	E _{AS}	16.2	mJ	
Maximum Power Dissipation ^b	T _C = 25 °C	D	4	W	
	T _C = 125 °C	P _D	1.3	VV	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	-55 to +175	°C	

THERMAL RESISTANCE RATINGS					
PARAMETER		SYMBOL	LIMIT	UNIT	
Junction-to-Ambient	PCB Mount ^c	R_{thJA}	110	°C/W	
Junction-to-Foot (Drain)		R_{thJF}	34	C/VV	

Notes

- a. Package limited.
- b. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- c. When mounted on 1" square PCB (FR4 material).

服务热线:400-655-8788

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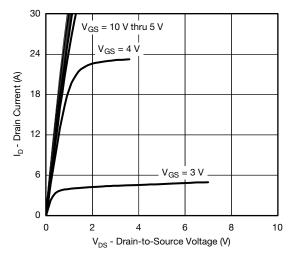
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		60	-	-	
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} =	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$		2.0	2.5	V
Gate-Source Leakage	I _{GSS}	V _{DS} =	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$		-	± 100	nA
		V _{GS} = 0 V	V _{DS} = 60 V	-	-	1	μA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{GS} = 0 V$	$V_{DS} = 60 \text{ V}, T_{J} = 125 ^{\circ}\text{C}$	-	-	50	
		$V_{GS} = 0 V$	$V_{DS} = 60 \text{ V}, T_{J} = 175 ^{\circ}\text{C}$	-	-	150	
On-State Drain Current ^a	I _{D(on)}	V _{GS} = 10 V	$V_{DS} \ge 5 V$	20	-	-	Α
		V _{GS} = 10 V	I _D = 4.5 A-	-	0.028	-	Ω
Drain-Source On-State Resistance a	R _{DS(on)}	V _{GS} = 10 V	I _D = 4.5 A, T _J = 125 °C	ı	0.066	-	
Than course on state hosteralise	1 103(011)	V _{GS} = 10 V	I _D = 4.5 A, T _J = 175 °C	-	0.081	-	
		$V_{GS} = 4.5 \text{ V}$	I _D = 4 A-	-	0.030	-	
Forward Transconductance f	9fs	$V_{DS} = 15 \text{ V}, I_D = 4.5 \text{ A}$		-	15	-	S
Dynamic ^b							
Input Capacitance	C _{iss}			-	600	750	
Output Capacitance	Coss	$V_{GS} = 0 V$	$V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$	-	110	140	pF
Reverse Transfer Capacitance	C _{rss}	1		-	50	62	
Total Gate Charge ^c	Qg			-	11.7	18	
Gate-Source Charge ^c	Q _{gs}	V _{GS} = 10 V	$V_{DS} = 30 \text{ V}, I_D = 5.3 \text{ A}$	-	1.8	2.7	nC
Gate-Drain Charge ^c	Q _{gd}			1	2.8	4.2	
Gate Resistance	R_g		f = 1 MHz	1.3	-	6	Ω
Turn-On Delay Time ^c	t _{d(on)}				7	11	
Rise Time ^c	t _r	$V_{DD} = 30 \text{ V, } R_L = 6.8 \Omega$ $I_D \cong 4.4 \text{ A, } V_{GEN} = 10 \text{ V, } R_g = 1 \Omega$		1	3.3	5	- ns
Turn-Off Delay Time ^c	t _{d(off)}			-	22.4	33.5	
Fall Time ^c	t _f			-	2.1	3.2	
Source-Drain Diode Ratings and Chara	acteristics ^b						
Pulsed Current ^a	I _{SM}			-	_	28	Α
Forward Voltage	V_{SD}	I _F = 2 A, V _{GS} = 0 V		-	0.75	1.1	V

Notes

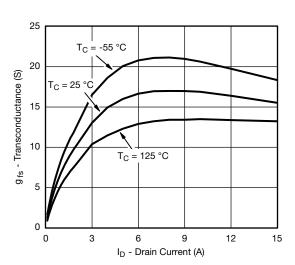
- a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %. b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.



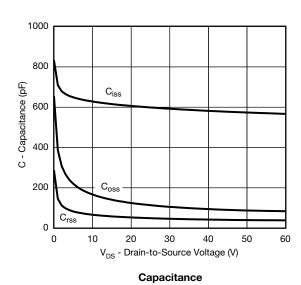
TYPICAL CHARACTERISTICS ($T_A = 25 \, ^{\circ}C$, unless otherwise noted)



Output Characteristics



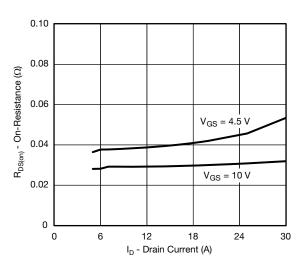
Transconductance



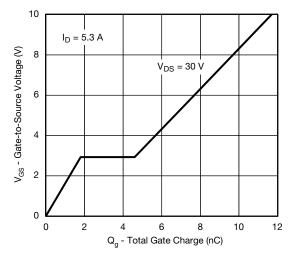
30
24

(x) the tip of the tip of

Transfer Characteristics



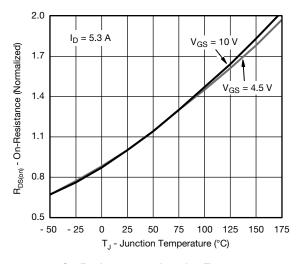
On-Resistance vs. Drain Current



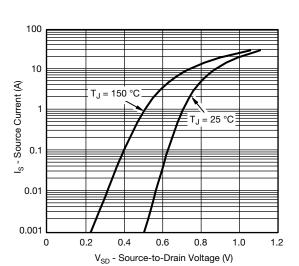
Gate Charge



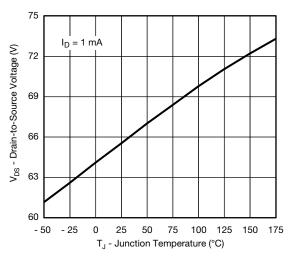
TYPICAL CHARACTERISTICS ($T_A = 25$ °C, unless otherwise noted)



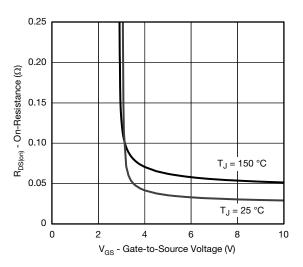
On-Resistance vs. Junction Temperature



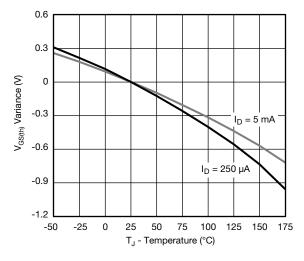
Source Drain Diode Forward Voltage



Drain Source Breakdown vs. Junction Temperature



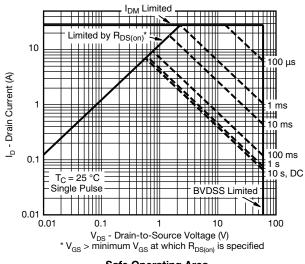
On-Resistance vs. Gate-to-Source Voltage



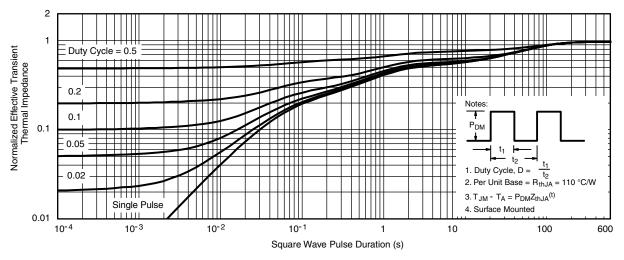
Threshold Voltage



THERMAL RATINGS ($T_A = 25$ °C, unless otherwise noted)



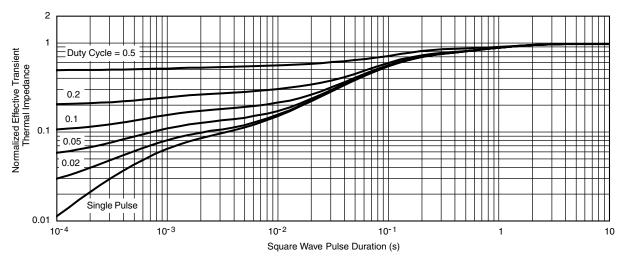
Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Ambient



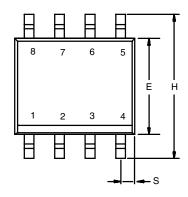
THERMAL RATINGS ($T_A = 25$ °C, unless otherwise noted)



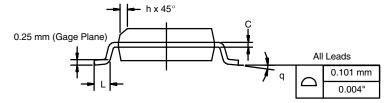
Normalized Thermal Transient Impedance, Junction-to-Foot



SOIC (NARROW): 8-LEADJEDEC Part Number: MS-012







	MILLIMETERS		INC	INCHES		
DIM	Min	Max	Min	Max		
Α	1.35	1.75	0.053	0.069		
A ₁	0.10	0.20	0.004	0.008		
В	0.35	0.51	0.014	0.020		
С	0.19	0.25	0.0075	0.010		
D	4.80	5.00	0.189	0.196		
E	3.80	4.00	0.150	0.157		
е	1.27 BSC		0.050 BSC			
Н	5.80	6.20	0.228	0.244		
h	0.25	0.50	0.010	0.020		
L	0.50	0.93	0.020	0.037		
q	0°	8°	0°	8°		
S	0.44	0.64	0.018	0.026		
FCN: C-06527-Bev. I. 11-Sep-06						

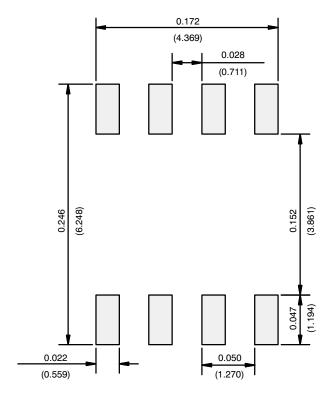
ECN: C-06527-Rev. I, 11-Sep-06

DWG: 5498

服务热线:400-655-8788 7



RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)



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